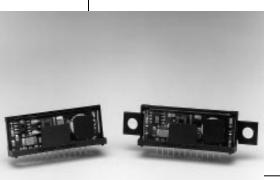
PT6305

Series

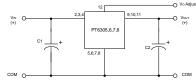
3 AMP HIGH-PERFORMANCE ADJUSTABLE ISR



- Single-Device 5V to 3V Power
- 85% Efficiency
- Small SIP Footprint: 0.36" x 2.00" x 0.60"(H)
- Wide Input Voltage Range: +4.5V to +9.0V
- Internal Short Circuit Protection
- Over-Temperature Protection

The PT6305N is Power Trends' new high performance +5V to +3.3V, 3 Amp, 12-Pin SIP (Single In-line-Package) Integrated Switching Regulator (ISR). This high-performance ISR allows easy integration of low-power 3.3V logic IC's into existing 5V systems without redesigning the central power supply. Only one external capacitor is required for proper operation. The PT6306,7,8 can be used to power high-speed data buses (+2.1V), or the new GTL (+1.2V) logic buses.

Standard Application



 C_1 = Optional electrolytic (100 μ F)

Pin-Out Information

Pin No.	Function
1	N/C
2	V_{in}
3	Vin
4	V _{in}
5	GND
6	GND

Pin No.	Function
7	GND
8	GND
9	V _{out}
10	V _{out}
11	V _{out}
12	Adjust
	(See page 40.)



Ordering Information

 $PT6305 \square = +3.3 \text{ Volts}$

PT6306□ = +1.8 Volts

 $PT6307 \square = +2.1 \text{ Volts}$

PT6308□ = +1.2 Volts

(For dimensions, see page 66.)

PT Series Suffix (PT1234X)

Case/Pin	Heat Tab Configuration None Side			
Configuration	None	Side		
Vertical Through-Hole	N	R		
Horizontal Through-Hole	Α	G		
Horizontal Surface Mount	С	В		

(See Thermal Application Notes on page 44 for heat tab

Specifications

Characteristics			PT6305 SERIES			
(T _A =25°C unless noted)	Symbols	Conditions	Min	Тур	Max	Units
Output Current	I_{o}	$4.5 \le V_{in} \le V_{in} MAX$	0.3	_	3.0**	ADC
Current Limit	$ m I_{cl}$	$V_{\rm in}$ = +5 V	_	3.6	5.0	ADC
Short Circuit Current	I_{sc}	$V_{\rm in}$ = +5 V	_	5.0	_	Apk
Input Voltage Range	$ m V_{in}$	$\begin{array}{ccc} 0.3 \text{A} \leq \text{I}_{\text{o}} \leq 3.0 \text{A} & \text{PT}6305 \text{N} \\ \text{PT}6306 \text{N} & \text{PT}6307 \text{N} \\ \text{PT}6307 \text{N} & \text{PT}6308 \text{N} \end{array}$	4.5 4.5 4.5 4.5		9 9 9 6.0	VDC VDC VDC VDC
Static Voltage Tolerance	V_{o}	$\begin{array}{c} V_{in} = +5 V, I_o = 3.0 A & PT6305 N \\ 0 ^{\circ} C \leq T_a \leq +70 ^{\circ} C & PT6306 N \\ PT6307 N & PT6308 N \end{array}$	3.2 1.7 2.0 1.1	3.3 1.8 2.1 1.2	3.4 1.9 2.2 1.3	VDC VDC VDC VDC
Line Regulation	Reg _{line}	$4.5V \le V_{in} \le 5.5V$, $I_{o} = 3.0A$	_	±25	±50	mV
Load Regulation	Reg _{load}	$V_{in} = +5V, 0.3 \le I_o \le 3.0A$	_	±25	±50	mV
Vo Ripple/Noise pk-pk	V _n	$V_{in} = 5V, I_o = 3.0A$	_	66	_	mV
Transient Response with C ₂ = 100μF	$egin{array}{c} t_{ m tr} \ V_{ m os} \end{array}$	$I_{\rm o}$ step between 1.5A and 3.0A $V_{\rm o}$ over/undershoot	_	200 200	_	μSec mV
Efficiency	η	$V_{in} = +5 V, I_o = 1.5 A & PT6305 N \\ PT6306 N \\ PT6307 N \\ PT6308 N \\ \\$		85 74 77 63		% % %
		$V_{in} = +5 V, I_o = 3.0 A & PT6305 N \\ PT6306 N & PT6307 N \\ PT6307 N & PT6308 N \\ \\ \end{array}$		80 68 72 57		% % %
Switching Frequency	f_{o}	$4.5 \le V_{in} \le V_{in} MAX$ $0.3A \le I_o \le 3.0A$	500	650	800	KHz
Operating Temperature	T_a	Free Air Convection (40-60 LFM) Over V _{in and} I _o Ranges	0	_	+70*	°C
Thermal Resistance	θ_{ja}	Free Air Convection (40-60 LFM)	_	25	_	°C/W
Storage Temperature	T_s	_	-40	_	+125	°C
Mechanical Shock		Per Mil-STD-883D, Method 2002.3 Condition A, 1 msec, Half Sine, mounted to a fixture			500	G's
Mechanical Vibration	Per Mil-STD	-883D, Method 2007.2 Condition A, 20-2000 Hz	_	_	15	G's
Weight	_	_	_	11.2	_	grams
Relative Humidity	_	Non-condensing	0	_	95	%

*See Thermal Derating chart. **The PT6305 Series can be easily paralleled to provide output current in multiples of 3 amps. Please contact a Power Trends' Application Engineer for the appropriate application note. Note: The PT6305 Series requires a 100µF electrolytic capacitor for proper operation in all applications.

C2 = Required 100µF electrolytic (No tantalum) See capacitor application note on page 43.

SHEETS

CHARACTERISTIC DATA

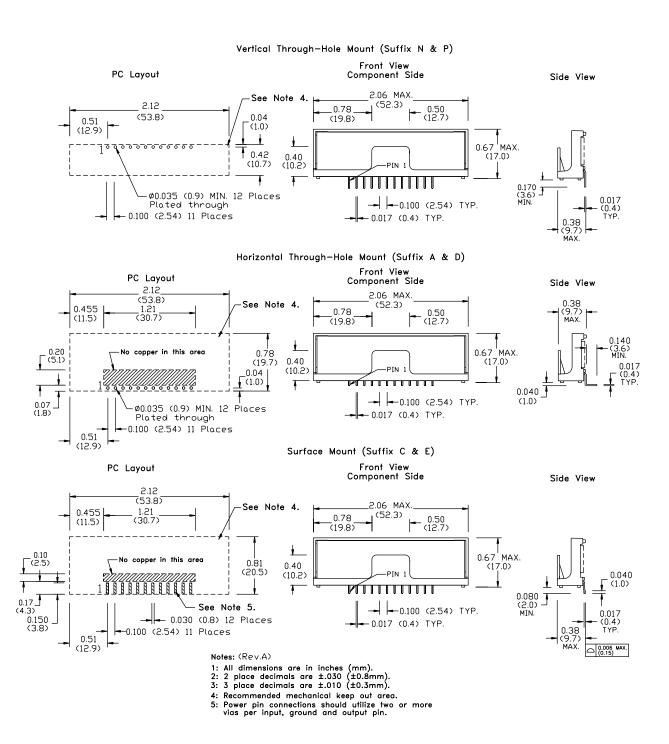
PT6305, 3.3 VDC PT6307, 2.1 VDC PT6308, 1.2 VDC (See Note 1) (See Note 1) (See Note 1) **Efficiency vs Output Current Efficiency vs Output Current Efficiency vs Output Current** 4:57 % % - - - · 4.5V Total District Efficiency. Efficiency 70 70 - - - 5.0V Efficiency 70 - - · 8.0V - - · 8.0V 60 - 9.0V 9.0V 50 1.5 lout-(Amps) 1.5 0.5 1.5 2 2.5 0.5 3 lout-(Amps) lout-(Amps) **Ripple vs Output Current Ripple vs Output Current Ripple vs Output Current** 100 100 - - 9.0V - - - 9.0V - - - · 6.0V (m (v) Ripple-(mV) --- 8.0V - - - 8.0\ 60 - - - 5.5V - - - 5.5V Ripple 20 20 0.5 2.5 1.5 1.5 1.5 2.5 lout-(Amps) **Minimum Input Voltage Minimum Input Voltage** (See Note 2) (See Note 2) **Minimum Input Voltage** (See Note 2) 4.5 4.5 4.5 4.3 4.25 4.25 4.1 Vin-(Volts) 3.9 3.75 3.7 0.5 15 2.5 0.5 15 2.5 0.5 1.5 2.5 Thermal Derating (Ta) Thermal Derating (T_a) Thermal Derating (Ta) (See Note 3) (See Note 3) (See Note 3) 2.5 2.5 2.5 lout-(Amps) 1.5 1.5 0.5 0.5 0.5 4.5 8.5 10.5 4.5 6.5 10.5 4.5 Vin-(Volts) Vin-(Volts) **Power Dissipation vs Output Current Power Dissipation vs Output Current Power Dissipation vs Output Current** 2.5 2.5 - - - 6.0V - 8.0V - · - 5.5V Pd-(Watts) 1.5 1.5 - 5.5V - - 5.5V - - · 5.0V - - - · 5.0V 4.5V - 4.5V 4.5V 0.5 0.5 2.5 0 1.5 0 0.5 1.5 2.5 1.5

Note 1: All data listed in the above graphs, except for derating data, has been developed from actual products tested at 25° C. This data is considered typical data for the ISR. Note 2: Minimum V_m data is typical and is not guaranteed. The data corresponds to a 2% output voltage drop. Note 3: Thermal derating graphs are developed in free air convection cooling of 40-60 LFM with no optional heat tab soldered in a printed circuit board. (See Thermal Application Notes).



PACKAGE INFORMATION AND DIMENSIONS

Revised 2/11/2000







www.ti.com

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
PT6305A	NRND	SIP MODULE	ECA	12		TBD	Call TI	Call TI	
PT6305B	NRND	SIP MODULE	ECK	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6305C	NRND	SIP MODULE	ECC	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6305N	NRND	SIP MODULE	ECD	12	12	TBD	Call TI	Level-1-215C-UNLIM	
PT6305R	NRND	SIP MODULE	ECE	12		TBD	Call TI	Call TI	
PT6306A	NRND	SIP MODULE	ECA	12		TBD	Call TI	Call TI	
PT6306B	NRND	SIP MODULE	ECK	12		TBD	Call TI	Call TI	
PT6306C	NRND	SIP MODULE	ECC	12		TBD	Call TI	Call TI	
PT6306G	NRND	SIP MODULE	ECG	12		TBD	Call TI	Call TI	
PT6306R	NRND	SIP MODULE	ECE	12		TBD	Call TI	Call TI	
PT6308A	NRND	SIP MODULE	ECA	12	12	TBD	Call TI	Level-1-215C-UNLIM	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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PACKAGE OPTION ADDENDUM

1-Aug-2011

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